



Product Change Notification - KSRA-28OGQI966

Date:

10 Oct 2019

Product Category:

8-bit Microcontrollers

Affected CPNs:**Notification subject:**

CCB 3661 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected Atmel products of AT90USB646 and AT90USB647 device families available in 64L VQFN package at NSEB assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected Atmel products of AT90USB646 and AT90USB647 device families available in 64L VQFN package at NSEB assembly site.

Pre Change:

Assembled using gold (Au) bond wire and G770HCD molding compound material.

Post Change:

Assembled using palladium coated copper with gold flash (CuPdAu) bond wire and G700LTD molding compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited / NSEB	UTAC Thai Limited / NSEB
Wire material	Au	CuPdAu
Die attach material	8600	8600
Molding compound material	G770HCD	G700LTD
Lead frame material	EFTEC 64T	EFTEC 64T

Impacts to Data Sheet:

None



Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire and G700LTD molding compound material.

Change Implementation Status:

In Progress

Estimated First Ship Date:

October 31, 2019 (date code: 1944)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	January 2019					-->	October 2019				
Workweek	01	02	03	04	05		40	41	42	43	44
Initial PCN Issue Date		X									
Qual Report Availability								X			
Final PCN Issue Date								X			
Estimated Implementation Date											X

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

February 01, 2019: Issued initial notification.

October 10, 2019: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on October 31, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-28OGQI966_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

AT90USB646-MU

AT90USB646-MUR

AT90USB647-MU

AT90USB647-MUR